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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10026639	FILING DATE 12/27/2001	CLASS 257	SUBCLASS	GAU 2841	EXAMINER 10026639 10026639
**APPLICANTS: Tatsuta Jun; Kube Masao; Kida Shinobu; Takami Shigenari; Kuzuhara Ikko; Tanaka Kyoji; Sanagawa Yoshiharu;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 2000-402818 12/28/2000					
PG-PUB		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO 217713US2	
TITLE : Semiconductor-chip mounting substrate and method of manufacturing the same					

U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
		Application Examiner	
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